

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S74	28	(scribing or scriber or scribe or scribed or dicing or dicer or diced or singulation or singulated or cleaver or cleaving or cleaved) near10 (computer or controller or memory) near8 (die or chip or circuit or ic or component or pellet or module) near3 (size or shape or dimension or location or locating or position)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:56
S73	5	"6522940".pn. "3814895".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:54
S72	315	438/460.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:59
S71	219	438/458.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:59
S67	250	438/113.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:42
S70	66	(chip or die or ic or integrated adj circuit or semiconductor) and (scribing or scribe or singulation or singulating or dicing or cleaving or cleaved) near8 (computer or memory or database) near8 (location or position or size or spacing or width or positioning or locating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:41
S69	120	(scribing or scribe or singulation or singulating or dicing or cleaving or cleaved) near8 (computer or memory or database) near8 (location or position or size or spacing or width or positioning or locating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:41
S68	1	(scribing or scribe or singulation or singulating or dicing or cleaving or cleaved) near8 (automated or automatic or robotic or computer) same (various or different or multiple or differing or changing) near5 (die or chip or device) near5 (size or area or location)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:39
S65	99	438/111.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:19
S64	99	438/110.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:12
S62	291	438/106.cor. and (automatic or automated or robotic or inline or in-line or pipeline)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 15:05
S63	6	"5549716".pn. "6465743".pn. "4674670".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:40

S61	120	438/107.cor. and (automatic or automated or robotic or inline or in-line or pipeline)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:27
S60	402	438/107.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:16
S59	492	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (wirebond\$3 or wire adj bond\$3) and (ball or solder or bump) near2 (attach\$4 or affix\$3 or mount\$3) and (encapsulat\$3 or encapsulant or molding or molded or molder) and (singulation or singulating or cutting or cutter or singulater or singulated or cleaving or cleaver or cleaved or cleavage or separation or separator or dicing or diced) and (anneal or annealing or annealer or thermal or heat or heating or heater or curing or cured or cure) and (clean or cleaning or cleaner or plasma or ashing or asher) and (test or testing or tester or tested or inspection or inspecting or inspected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:16
S47	430	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (wirebond\$3 or wire adj bond\$3) and (ball or solder or bump) near2 (attach\$4 or affix\$3 or mount\$3) and (encapsulat\$3 or encapsulant or molding or molded or molder) and (singulation or singulating or cutting or cutter or singulater or singulated or cleaving or cleaver or cleaved or cleavage or separation or separator or dicing or diced) and (anneal or annealing or annealer or thermal or heat or heating or heater or curing or cured or cure) and (clean or cleaning or cleaner or plasma or ashing or asher) and (test or testing or tester or tested or inspection or inspecting or inspected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 13:31
S58	320	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (testing or test or tested or inspection or inspecting or inspected or sorting or sorted) and (chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 12:58
S44	293	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (testing or test or tested or inspection or inspecting or inspected or sorting or sorted) and (chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 12:42
S57	262	(automated or automatic or robotic) near2 (chip or die or ic) near3 (conveyor or conveying or conveyance or movement or mover or moving or transfer or transferring or transferral or handling or handler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:08
S37	250	(automated or automatic or robotic) near2 (chip or die or ic) near3 (conveyor or conveying or conveyance or movement or mover or moving or transfer or transferring or transferral or handling or handler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:07
S56	313	(die or chip or ic) near3 (strip or array or panel or tape or reel) near15 (assembly or assembling or packaging or packaged or assembled) near15 (automated or automatic or robotic or computerized or in-line or inline)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 10:39
S34	298	(die or chip or ic) near3 (strip or array or panel or tape or reel) near15 (assembly or assembling or packaging or packaged or assembled) near15 (automated or automatic or robotic or computerized or in-line or inline)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 10:39

S55	221	(automatic or automated or automating or robotic) near4 (packaging or package or assembly) same (die or chip or ic) near3 (attaching or attach or attached or bonding or bonded or bond) same (wirebonding or wirebond or wire near bonding or wire near bonded or wirebonded or wire near bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 10:19
S21	206	(automatic or automated or automating or robotic) near4 (packaging or package or assembly) same (die or chip or ic) near3 (attaching or attach or attached or bonding or bonded or bond) same (wirebonding or wirebond or wire near bonding or wire near bonded or wirebonded or wire near bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 10:19
S54	114	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or back adj end or line or "in-line" or back near line) near2 (system or apparatus or machine) and (attachment or attaching or flip adj chip or bonding or bonded or adhering) same (cure or curing or thermal or plasma or anneal or annealing or cured or annealed) and (singulating or singulation or singulated or cutting or cut or sawing or sawed or dicing or diced or cleaving or cleavage or cleaved) same (test or testing or tested or sorting or sorted or sorter or sort)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 10:09
S12	102	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or back adj end or line or "in-line" or back near line) near2 (system or apparatus or machine) and (attachment or attaching or flip adj chip or bonding or bonded or adhering) same (cure or curing or thermal or plasma or anneal or annealing or cured or annealed) and (singulating or singulation or singulated or cutting or cut or sawing or sawed or dicing or diced or cleaving or cleavage or cleaved) same (test or testing or tested or sorting or sorted or sorter or sort)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 10:08
S53	204	(ic or integrated adj circuit or die or chip) near5 (back near end or end near line or back near line) and (bonding or bonded or attachment or flip adj chip or attaching or adhering) and (plasma or cure or curing or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 09:49
S8	182	(ic or integrated adj circuit or die or chip) near5 (back near end or end near line or back near line) and (bonding or bonded or attachment or flip adj chip or attaching or adhering) and (plasma or cure or curing or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 09:49